ON Semiconductor®



LCD and Camera EMI Filter Array with ESD Protection

CM1631

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 35dB attenuation (typical) at 1 GHz
- uDFN package with 0.40mm lead pitch:
 - •4-ch. = 8-lead uDFN
 - •6-ch. = 12-lead uDFN
 - •8-ch. = 16-lead uDFN
- Tiny uDFN package size:
 - 8-lead: 1.70mm x 1.35mm x 0.50mm
 - 12-lead: 2.50mm x 1.35mm x 0.50mm
 - 16-lead: 3.30mm x 1.35mm x 0.50mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free finishing, RoHS compliant

Applications

- LCD and Camera data lines in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- · Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules

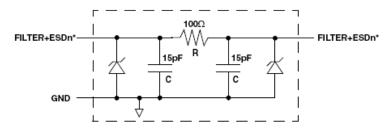
Product Description

The CM1631 is a family of pi-style EMI filter arrays with ESD protection, which integrates four, six, or eight filters (C-R-C) in a small form factor, uDFN 0.40mm pitch package. The CM1631 has component values of 15pF-100W-15pF per channel with a cut-off frequency of 120MHz, and can be used in applications with data rates up to 48Mbps. The device includes ESD diodes on every pin, that provide a very high level of protection for sensitive electronic components against possible electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of ±15kV, which is well beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges greater than ±30kV.

These devices are particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of their small package and easy-to-use pin assignments. In particular, the CM1631 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

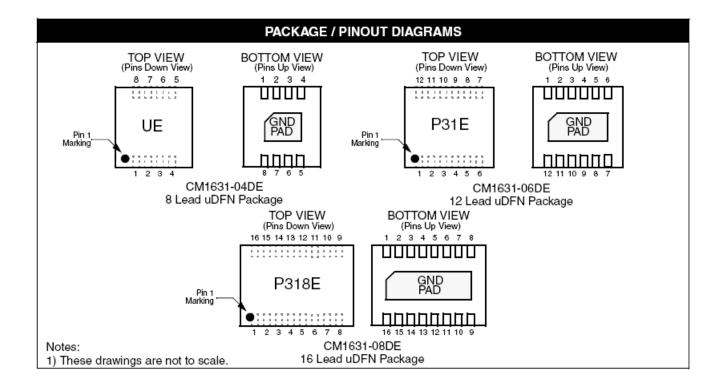
The CM1631 is housed in space-saving, ultra-low-profile 8-, 12- and 16-lead uDFN packages with a 0.40mm pitch and is available with lead-free finishing. This smaller size uDFN package provides up to 42% board space saving vs. the 0.50mm pitch uDFN packages.

Electrical Schematic



* See Package/Pinout Diagram for expanded pin information.

1 of 4, 6 or 8 EMI/RFI + ESD Channels



	PIN DESCRIPTIONS												
DEVICE PIN(s)					DEVICE PIN(s)								
-04	-06	-08	NAME	DESCRIPTION		-04	-06	-08	NAME	DESCRIPTION			
1	1	1	FILTER1	Filter + ESD Channel 1		8	12	16	FILTER1	Filter + ESD Channel 1			
2	2	2	FILTER2	Filter + ESD Channel 2		7	11	15	FILTER2	Filter + ESD Channel 2			
3	3	3	FILTER3	Filter + ESD Channel 3		6	10	14	FILTER3	Filter + ESD Channel 3			
4	4	4	FILTER4	Filter + ESD Channel 4		5	9	13	FILTER4	Filter + ESD Channel 4			
	5	5	FILTER5	Filter + ESD Channel 5			8	12	FILTER5	Filter + ESD Channel 5			
	6	6	FILTER6	Filter + ESD Channel 6			7	11	FILTER6	Filter + ESD Channel 6			
		7	FILTER7	Filter + ESD Channel 7				10	FILTER7	Filter + ESD Channel 7			
		8	FILTER8	Filter + ESD Channel 8				9	FILTER8	Filter + ESD Channel 8			
	SND PA	ΔD	GND	Device Ground									

Ordering Information

PART NUMBERING INFORMATION									
	Lead-free Finish								
Pins	Package	Ordering Part Number ¹	Part Marking						
8	uDFN-8	CM1631-04DE	UE						
12	uDFN-12	CM1631-06DE	P31E						
16	uDFN-16	CM1631-08DE	P318E						

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	RATING	UNITS					
Storage Temperature Range	-65 to +150	°C					
DC Power per Resistor	100	mW					
DC Package Power Rating	500	mW					

STANDARD OPERATING CO	ONDITIONS	
PARAMETER	RATING	UNITS
Operating Temperature Range	-40 to +85	°C

	ELECTRICAL OP	ERATING CHARACTERIS	STICS	(SEE NOTE	1)	
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R	Resistance		80	100	120	Ω
C _{TOTAL}	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	24	30	36	pF
С	Capacitance C	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	12	15	18	pF
V_{DIODE}	Standoff Voltage	$I_{\text{DIODE}} = 10 \mu A$		6.0		V
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} = 3.3V		0.1	1.0	μА
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10 \text{mA}$ $I_{LOAD} = -10 \text{mA}$	5.6 -0.4	6.8 -0.8		V V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4- 2 Level 4	Note 2	±30 ±15			kV kV
R _{DYN}	Dynamic Resistance Positive Negative			2.3 0.9		Ω
f _c	Cut-off Frequency $Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega$	Channel R = 100Ω , Channel C = $15pF$		110		MHz
A _{1GHz}	Absolute Attenuation @ 1GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega,$ DC Bias = 0V; Notes 1 and 3		35		dB
A _{800MHz - 6GHz}	Absolute Attenuation @ 800MHz to 6GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega$, $Z_{\text{LOAD}} = 50\Omega$, DC Bias = 0V; Notes 1 and 3		30		dB

Note 1: $T_A=25^{\circ}C$ unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Note 3: Attenuation / RF curves characterized by a network analyzer using microprobes.

Performance Information

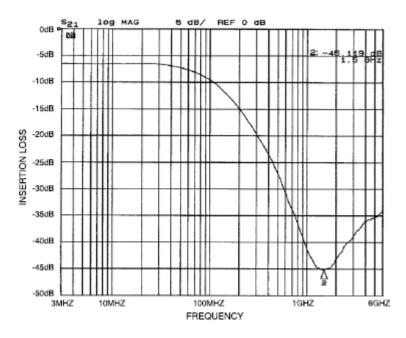


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1631-04DE)

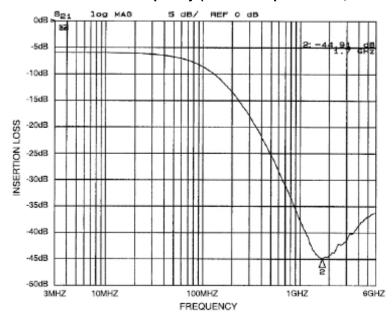


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1631-04DE)

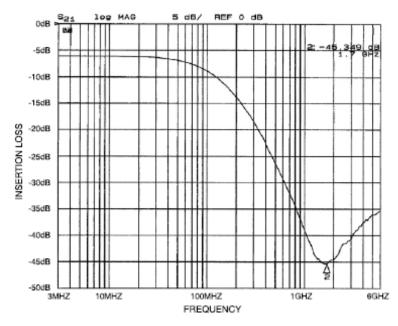


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1631-04DE)

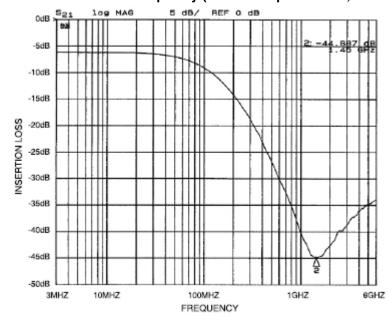


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1631-04DE)

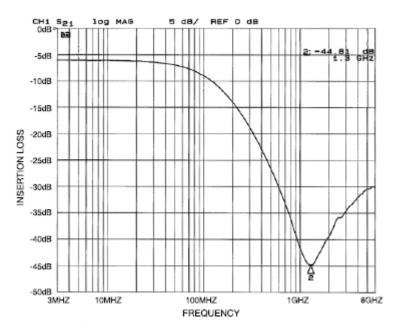


Figure 5. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1631-06DE)

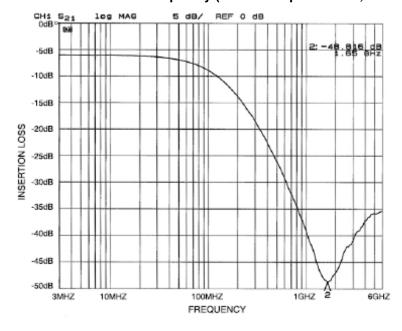


Figure 6. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1631-06DE)

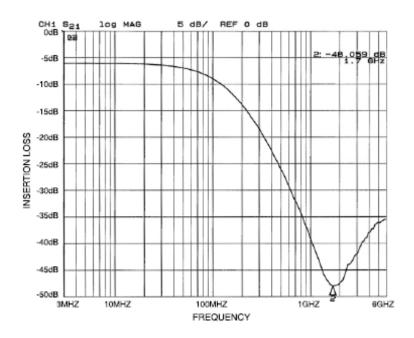


Figure 7. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1631-06DE)

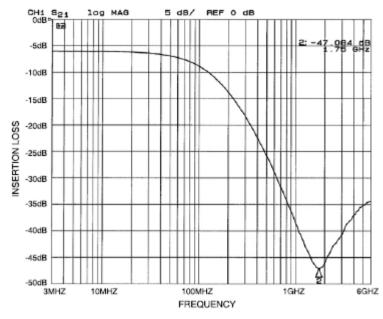


Figure 8. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1631-06DE)

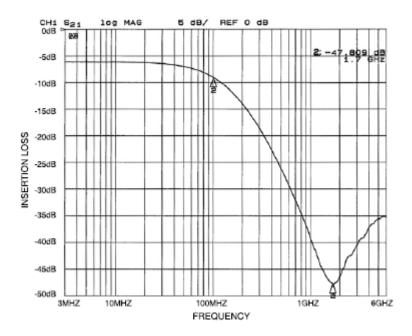


Figure 9. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1631-06DE)

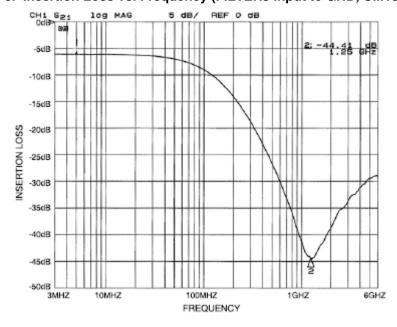


Figure 10. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1631-06DE)

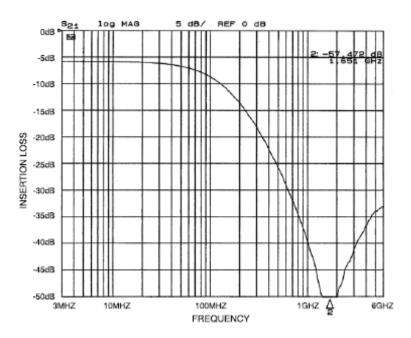


Figure 11. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1631-08DE)

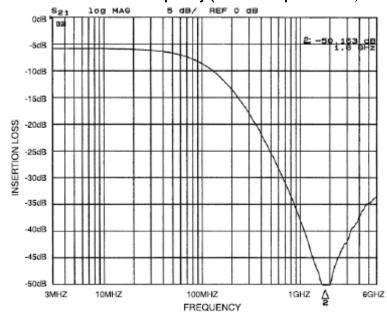


Figure 12. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1631-08DE)

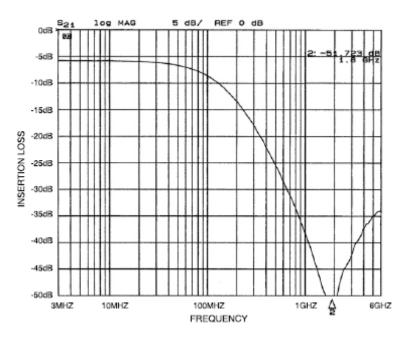


Figure 13. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1631-08DE)

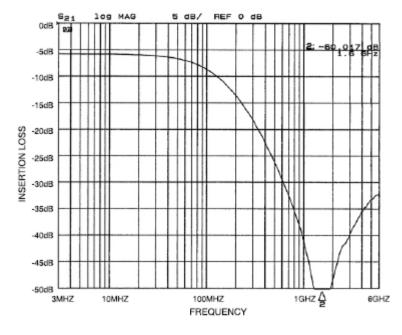


Figure 14. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1631-08DE)

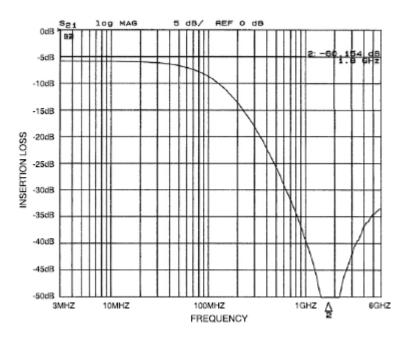


Figure 15. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1631-08DE)

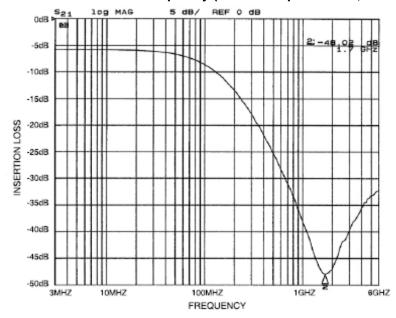


Figure 16. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1631-08DE)

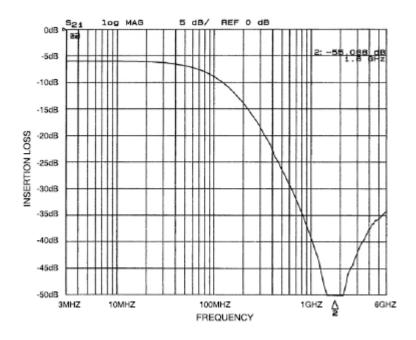


Figure 17. Insertion Loss vs. Frequency (FILTER7 Input to GND, CM1631-08DE)

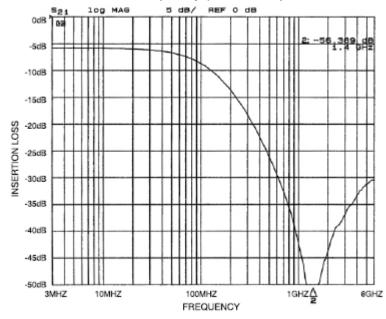


Figure 18. Insertion Loss vs. Frequency (FILTER8 Input to GND, CM1631-08DE)

Typical Diode Capacitance vs. Input Voltage

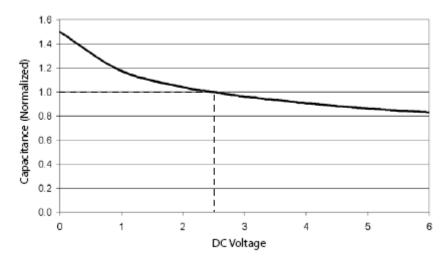


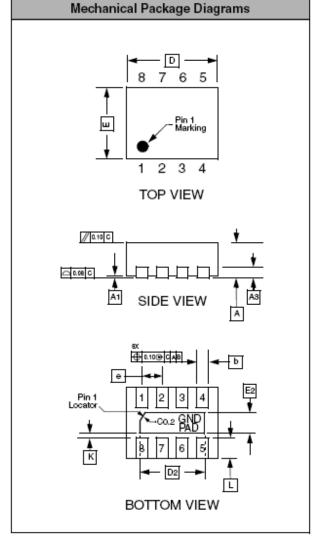
Figure 19. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5VDC and 25°C)

Mechanical Details

uDFN-08 Mechanical Specifications

Dimensions for the CM1631-04DE supplied in a 8-lead, 0.4mm pitch uDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS				
Package		uDFN							
JEDEC No.			MO-	229C					
Leads				8					
Dim.	IV	lillimete	rs		Inches				
5	Min	Nom	Max	Min	Nom	Max			
Α	0.45	0.50	0.55	0.018	0.020	0.022			
A 1	0.00	0.02	0.05	0.000	0.001 0.002				
А3	C).127 RE	F	O	.005 RE	F			
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	1.60	1.70	1.80	0.063	0.067	0.071			
D2	1.10	1.20	1.30	0.043	0.047	0.051			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	0	.016 BS	C			
К	(0.22 RE	F	O	.009 RE	F			
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel		3000 pieces							
	Contro	olling din	nension:	millimet	ers				

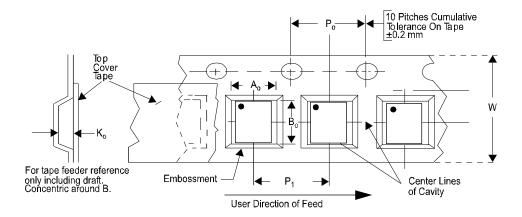


Dimensions for 8-Lead, 0.4mm pitch uDFN package

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Tape and Reel Specifications

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1631-04DE	1.70 X 1.35 X 0.50	1.95 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm

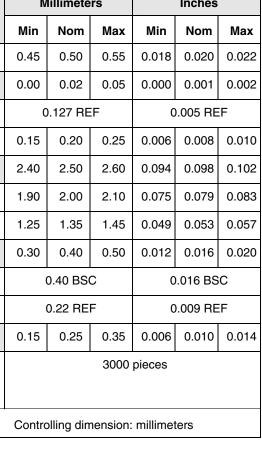


Mechanical Details (cont'd)

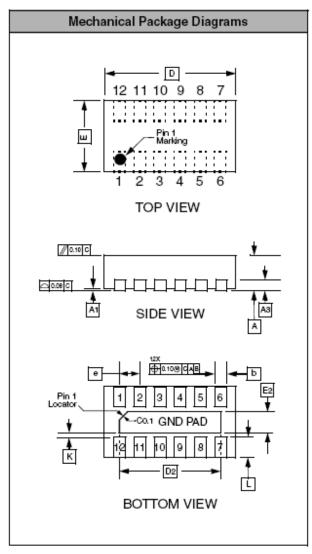
uDFN-12 Mechanical Specifications

Dimensions for the CM1631-06DE supplied in a 12-lead, 0.4mm pitch uDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS					
Package		uDFN								
JEDEC No.			MO-	229C						
Leads			1	12						
Dim.	IV	lillimete	rs		Inches					
Diiii.	Min	Nom	Max	Min	Nom	Max				
Α	0.45	0.50	0.55	0.018	0.020	0.022				
A1	0.00	0.02	0.05	0.000	0.001 0.002					
А3	C).127 RE	F	O	.005 RE	:F				
b	0.15	0.20	0.25	0.006	0.008	0.010				
D	2.40	2.50	2.60	0.094	0.098	0.102				
D2	1.90	2.00	2.10	0.075	0.079	0.083				
E	1.25	1.35	1.45	0.049	0.053	0.057				
E2	0.30	0.40	0.50	0.012	0.016	0.020				
е	(0.40 BS	С	0	.016 BS	С				
К	(0.22 RE	F	0	.009 RE	:F				
L	0.15	0.25	0.35	0.006	0.010	0.014				
# per tape and reel			3000	000 pieces						
	Contro	olling din	nension:	millimet	ers					



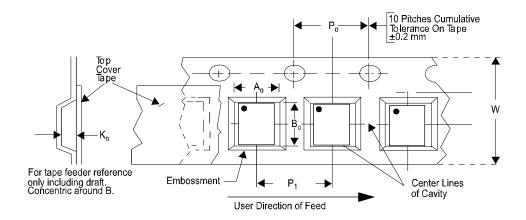
This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.



Dimensions for 12-Lead, 0.4mm pitch uDFN Package

Tape and Reel Specifications

PAR	T NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1	631-06DE	2.50 X 1.35 X 0.50	2.75 X 1.60 X 0.70	8mm	178mm (7")	3000	4mm	4mm

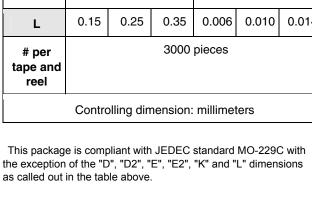


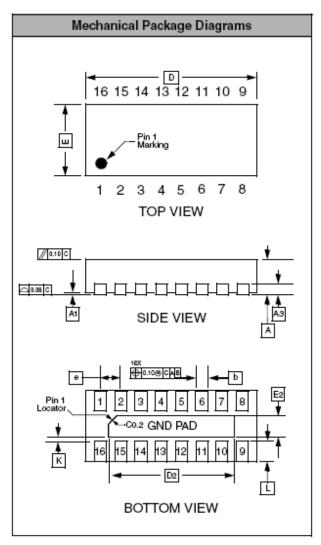
Mechanical Details (cont'd)

uDFN-16 Mechanical Specifications

Dimensions for the CM1631 supplied in a 16-lead, 0.4mm pitch uDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS					
Package		uDFN								
JEDEC No.			MO-	229C						
Leads			1	16						
Dim.	IV	lillimete	rs		Inches					
Diiii.	Min	Nom	Max	Min	Nom	Max				
Α	0.45	0.50	0.55	0.018	0.020	0.022				
A1	0.00	0.02	0.05	0.000	0.001	0.002				
А3	C).127 RE	F	0	.005 RE	F				
b	0.15	0.20	0.25	0.006	0.008	0.010				
D	3.20	3.30	3.40	0.126	0.130	0.134				
D2	2.70	2.80	2.90	0.106	0.110	0.114				
E	1.25	1.35	1.45	0.049	0.053	0.057				
E2	0.30	0.40	0.50	0.012	0.016	0.020				
е	(0.40 BS	0	0	.016 BS	C				
К	(0.22 RE	F	0	.009 RE	F				
L	0.15	0.25	0.35	0.006	0.010	0.014				
# per tape and reel		3000 pieces								
	Contro	olling din	nension:	millimet	ers					

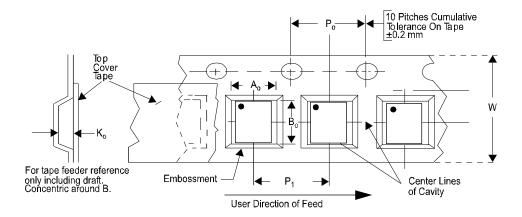




Dimensions for 16-Lead, 0.4mm pitch uDFN package

Tape and Reel Specifications

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1631-08DE	3.30 X 1.35 X 0.50	3.50 X 1.55X 0.70	8mm	178mm (7")	3000	4mm	4mm



CM1631

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